

In the Specification

Please add the following two paragraphs before the paragraph beginning at page 1, line 3 of the specification ("Background of the Invention").

Reference to Related Applications

A1 This application is the national stage of International Application No. PCT/US00/25118, filed September 13, 2000, which is a continuation-in-part of U.S. Application No. 09/395,869, filed September 14, 1999. The disclosure of each of these applications is incorporated herein by reference.

Please replace the paragraph beginning at page 20, line 19 by the following paragraph.

A2 Figure 6 shows in cross-section a composite device 2 as in Figure 5 soldered to traces 41 and 43 on an insulating substrate 9.

Please replace the paragraph beginning at page 22, line 8 by the following paragraph.

A3 Figure 21 illustrates a composite device which has only one internal electrode 16, formed from a stack with only one internal conductive surface. A laminar element 17 is combined with the laminar element 76. The laminar elements can be pressed together to form a bond, so that no third laminar element is required to secure the laminar elements together. For example, 17 can comprise a PTC element and 76 can comprise a dielectric substrate with adhesive properties.

Please replace the paragraph beginning at page 24, line 6 by the following paragraph.

A4 One surface of one foil layer of each of two laminates was patterned using an etching technique in which the surface was first coated with an etch resist, then imaged in a desired pattern. The etch resist was developed and etching was accomplished using cupric chloride before the resist was stripped away. These same foil layers were patterned to define the periphery of the individual devices and the residual conductive members. In addition, the outer edges of the metal foil on the laminate were etched to provide an alternating cross

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Cont

directional pattern around the perimeter, as shown in Figure 2. Paths providing electrical continuity were utilized during the subsequent electrolytic plating of Sn/Pb.

Please replace the two paragraphs beginning at page 26, line 11 by the following two paragraphs.

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A stacked assembly in accordance with Figure 26 was prepared by the following method. One laminate having a thickness of about 0.198 mm (0.0078 inch) was prepared by attaching a nickel/copper foil having a thickness of about 0.0356 mm (0.0014 inch) to both major sides of a 0.127 mm (0.005 inch)-thick sheet of conductive polymer. The conductive polymer was prepared by mixing about 37% by volume carbon black (Raven™ 430) with about 10.5% by volume high density polyethylene (LB832, manufactured by Equistar) and about 52.5% copolymer (EBA705, manufactured by Equistar), as in Example 1, and then extruding into sheet and laminating in a continuous process. The laminated sheet was cut into individual laminates of 0.10 m x 0.41 m (4 inch x 16 inch).

The laminate was drilled with registration holes as in Example 1 and with holes having a diameter of 1.27 mm (0.050 inch) to create apertures in the laminate. Four layers of 0.038 mm (0.0015 inch)-thick layer of epoxy pre-preg (44N Multifilm, available from Arlon) and two layers of 1 oz Cu foil treated as in Example 2 were also drilled with registration holes suitable for alignment.

In the Claims

Please cancel claims 1 to 17.

In the Drawings

Please replace Figure 6 on page 3/9 of the drawings by Figure 6 on replacement sheet 3/9.